

IN THE CLAIMS:

C1 Claim 1, line 2, after "percent Sn" please insert -- wherein said alloy contains substantially no Ag or antimony --

Claim 7, line 1, please delete "solved".

Claim 8, line 1, please delete "solved".

Claim 9, line 1, please delete "solved".

Claim 10, line 1, please delete "solved".

Claim 11, line 1, please delete "solved".

Claim 12, line 1, please delete "solved".

10/13. (Once amended) A lead-free solder alloy comprising 0.1 - 2 wt% Cu, 0.002 - 1 wt% Ni, 0.001-1 wt% Ge, and the remaining percent Sn [according to claim 1 wherein 0.001-1 wt% Ge is further added].

11/14. (Once amended) A lead-free solder alloy according to claim [2 wherein 0.001-1 wt% Ge is further added] 13 wherein the weight percentage of Cu falls within a range from 0.3 to 0.7 percent.

12/15. (Once amended) A lead-free solder alloy according to claim [3 wherein 0.001-1 wt% Ge is further added] 14 wherein the weight percentage of Ni falls within a range from 0.04 to 0.1 percent.

Remarks

Indication of allowable subject matter in claims 13-15 is gratefully acknowledged. Applicant has amended the application to claim priority under 35 U.S.C. § 120 as a continuation of PCT/JP99/01229, that was co-pending with the application. Applicant includes a copy of the PCT application cover sheet, the search report, a translation, the PCT claims, drawings, and description. Applicant is in the process of procuring certified copies of

RECEIVED
SEP - 5 2000
TO 1700 MAIL ROOM